

ABSTRACT OF THE DISCLOSURE

In the present invention, a main chuck comprises a table for performing the delivery of a wafer W to and from a pincette and a plurality of lift pins for allowing the wafer W to rise from the surface of the table. At least one lift pin positioned on the side of the pincette is made longer and positioned higher than the other lift pins so as to permit the wafer W to be supported above the table in an inclined manner.